

# Hiner-pack® MCS-PP Cassette 150 mm

*Maintains wafer stability through transport, inspection, and fabrication stages*

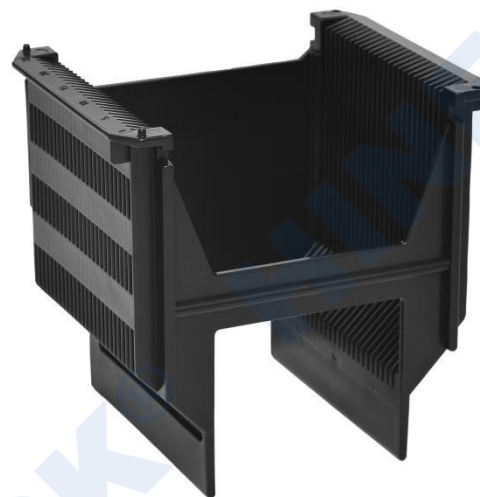
Engineered for semiconductor wafer handling, wafer cassettes—sometimes referred to as wafer boats—are used for in-fab wafer transfer and temporary storage. Designed to accommodate wafers of consistent size, they are molded from high-grade polypropylene for strength and thermal resistance. Available in natural or conductive material, these cassettes integrate seamlessly with automated wafer processing equipment, ensuring precise alignment, contamination control, and operational reliability. Commonly used in general wafer handling, they can be paired with wafer storage boxes to maximize wafer protection during movement.

## SPECIFICATIONS

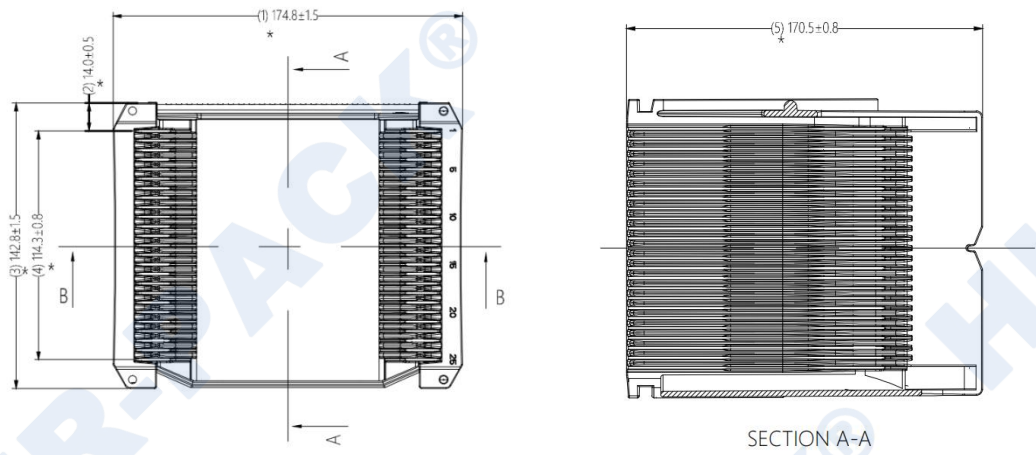
- 174.8 mm L × 142.8 mm W × 170.5 mm H (6.88" × 5.62" × 6.71")
- Maximum load capacity is 25 pieces

## FEATURES & BENEFITS

- Lightweight PP construction ideal for in-fab transfer
- Compatible with automation and cassette-standard tools
- Available in multiple colors to facilitate process identification
- Available in multiple materials to cope with different requirements for chemical resistance
- Moderate temperature resistance material



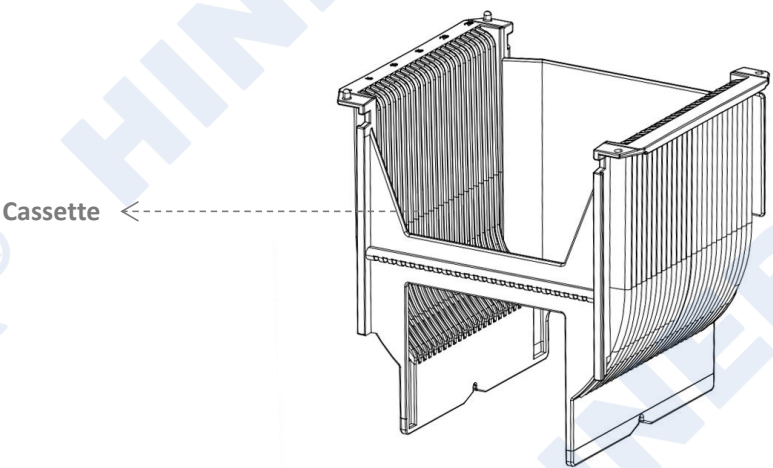
DIMENSION



BASIC INFORMATION

Part Number	Material	Wafer Size
MCS-6/25-BL-B	PP	150 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

## TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183-1 (23°C)	1.0 g/cm <sup>3</sup>
Melt Index (350°C/5kg)	ASTM D-1238	15.0 g/10min
Shrinkage Percentage	ISO 2577	1.2~1.6 %
Tensile Strength	ISO 527-2 (50mm/min)	25 MPa
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Strength (Fracture)	ISO 178 (2mm/min)	27 MPa
Flexural Modulus	ISO 178 (2mm/min)	1150 MPa
LZOD Notch Impact Strength (3.2mm)	ISO 180 (23°C)	30 kJ/m <sup>2</sup>
Surface Resistivity	ASTM D-257	1.0×10 <sup>4</sup> ~1.0×10 <sup>9</sup> Ω/sq
Flame Retardant Rating	UL 94	HB Class

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



Hiner-pack®

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